



Appl. No. 09/736,225  
Amendment dated: July 21, 2003  
Reply to OA of: April 24, 2003

2811  
#13/D  
8/6/03  
Smith

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : HUANG et al.  
Appl. No. : 09/736,225  
Filed : December 15, 2000  
Title : SEMICONDUCTOR PACKAGE WITHOUT SUBSTRATE AND  
METHOD OF MANUFACTURING SAME  
TC/A.U. : 2811  
Examiner : N. Parekh  
Docket No.: : HUAN3033/REF

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of April 24, 2003, in connection with the above-identified application. This response is timely filed.

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks being on page 5 of this paper.

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